

In the Claims:

Please cancel claims 12-14.

Sub B
Claim 1 (amended). A method for producing an electrical connection between integrated circuits, which comprises:

providing a first integrated circuit having a terminal[,] and a signal terminal;

forming an electrically conductive connection between the terminal and the signal terminal of the first integrated circuit;

providing a second integrated circuit having a terminal that is coupled to a protective structure for protecting against electrostatic discharges;

disposing the first and second integrated circuits adjacent one another;

electrically connecting the signal terminal of the first integrated circuit to the terminal of the second integrated circuit; and

cont
a1
severing the electrically conductive connection between the terminal and the signal terminal of the first integrated circuit using an energy pulse.

Please add the following claims:

--15. The method according to claim 1, which comprises providing the protective structure as a structure that becomes conducting to dissipate electrostatic discharges.

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16. The method according to claim 1, which comprises providing the energy pulse in the form of a current which is applied to the electrically conductive connection.

17. The method according to claim 1, which comprises providing the energy pulse in the form of a laser beam which is applied to the electrically conductive connection.

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18. The method according to claim 1, which comprises performing the severing step before packaging the first integrated circuit and the second integrated circuit.--

Remarks:

Reconsideration of the application is requested.

Claims 1-11 and 15-18 are now in the application. Claim 1 has been amended, claims 15-18 have been added, and claims 12-14